

PS2705-1

HIGH ISOLATION VOLTAGE AC INPUT RESPONSE
TYPE SOP MULTI PHOTOCOUPLER

R08DS0093EJ0400
Rev.4.00
July 3, 2026

DESCRIPTION

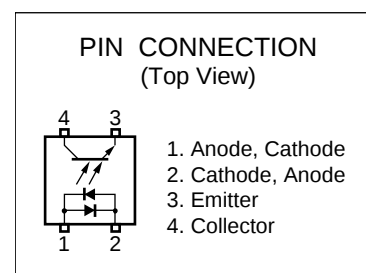
The PS2705-1 is an optically coupled isolator containing a GaAs light emitting diode and an NPN silicon phototransistor.

This package is SOP (Small Outline Package) type and has shield effect to cut off ambient light.

It is designed for high density mounting applications.

FEATURES

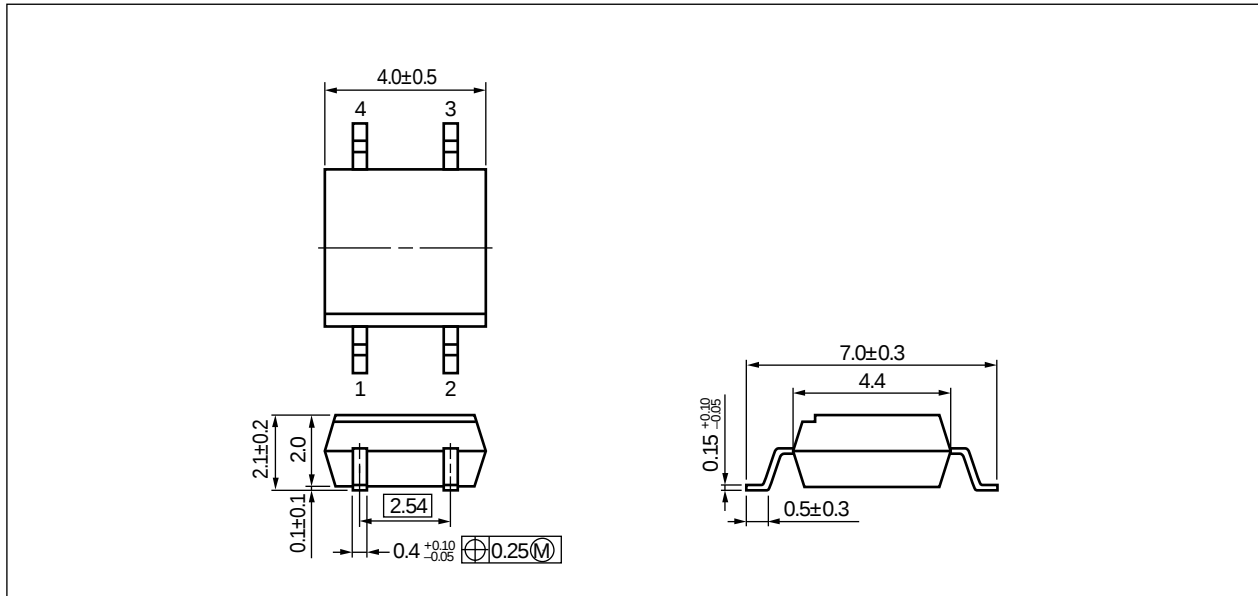
- AC input response
- High isolation voltage (BV = 3 750 Vr.m.s.)
- High current transfer ratio (CTR = 100 % TYP.)
- SOP (Small Outline Package) type
- High-speed switching ($t_r = 3 \mu s$ TYP., $t_f = 5 \mu s$ TYP.)
- Ordering number of taping product : PS2705-1-F3
- Pb-free product
- Safety standards
 - UL approved: UL 1577, Single protection
 - CSA approved: CSA C22.2 No. 62368-1, Basic/Supplementary insulation
 - BSI approved: BS EN IEC 62368-1, Basic/Supplementary insulation
 - SEMKO approved: EN IEC 62368-1, IEC 62368-1, Basic/Supplementary insulation
 - NEMKO approved: EN IEC 62368-1, Basic/Supplementary insulation
 - FIMKO approved: EN IEC 62368-1, Basic/Supplementary insulation
 - DEMKO approved: EN IEC 62368-1, Basic/Supplementary insulation
 - VDE approved: DIN EN IEC 60747-5-5 (Option)



APPLICATIONS

- Hybrid IC
- Telephone/FAX
- FA/OA equipment
- Programmable logic controllers
- Power supply

PACKAGE DIMENSIONS (UNIT: mm)

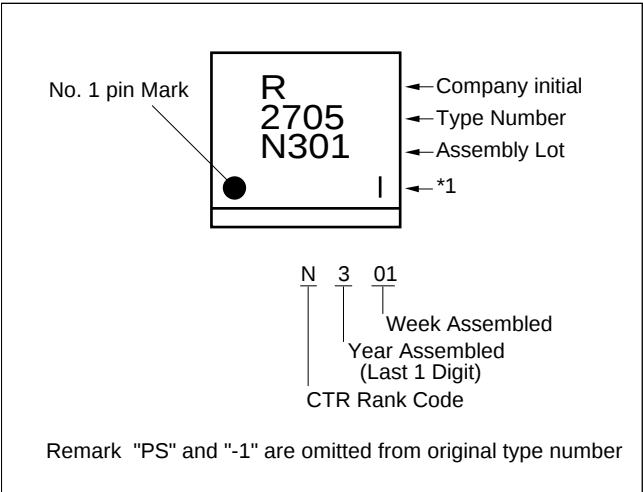


Weight : 0.08 g (TYP.)

PHOTOCOUPLER CONSTRUCTION

Parameter	MIN.
Air Distance	5 mm
Creepage Distance	5 mm
Isolation Distance	0.3 mm

MARKING EXAMPLE



Note: Bar indication contents of *1

Made in Taiwan (*1: No indication)	
Made in Japan (*1: " " (Vertical bar))	

ORDERING INFORMATION

Part Number	Order Number *1	Solder Plating Specification	Packing Style	Safety Standard Approval	Application Part Number *2
PS2705-1-F3	PS2705-1-F3-A	Pb-Free	Embossed Tape 3 500 pcs/reel	Standard products (UL, BSI, CSA, SEMKO, NEMKO, FIMKO, DEMKO Approved)	PS2705-1
PS2705-1-V-F3	PS2705-1-V-F3-A		Embossed Tape 3 500 pcs/reel	UL, CSA, BSI, SEMKO, NEMKO, FIMKO, DEMKO, VDE Approved	

Notes: *1. When specifying CTR rank, please add "-CTR rank" after Order Number.

ex. L rank : PS2705-1-F3-A-L

Notes: *2. For the application of the safety standard, the following part number should be used.

ABSOLUTE MAXIMUM RATINGS ($T_A = 25\text{ }^{\circ}\text{C}$, unless otherwise specified)

Parameter		Symbol	Ratings	Unit
Diode	Forward Current (DC)	I_F	± 50	mA
	Power Dissipation Derating	$\Delta P_D/^{\circ}\text{C}$	0.8	mW/ $^{\circ}\text{C}$
	Power Dissipation	P_D	80	mW
	Peak Forward Current *1	I_{FP}	± 1	A
Transistor	Collector to Emitter Voltage	V_{CEO}	40	V
	Emitter to Collector Voltage	V_{ECO}	6	V
	Collector Current	I_C	80	mA
	Power Dissipation Derating	$\Delta P_C/^{\circ}\text{C}$	1.5	mW/ $^{\circ}\text{C}$
	Power Dissipation	P_C	150	mW
Isolation Voltage *2		BV	3 750	Vr.m.s.
Operating Ambient Temperature		T_A	-55 to +100	$^{\circ}\text{C}$
Storage Temperature		T_{stg}	-55 to +150	$^{\circ}\text{C}$

Note: *1. PW = 100 μs , Duty Cycle = 1 %

*2. AC voltage for 1 minute at $T_A = 25\text{ }^{\circ}\text{C}$, RH = 60 % between input and output.

Pins 1-2 shorted together, 3-4 shorted together.

ELECTRICAL CHARACTERISTICS (T_A = 25°C)

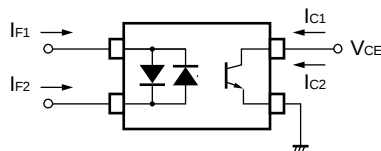
	Parameter	Symbol	Conditions	MIN.	TYP.	MAX.	Unit
Diode	Forward Voltage	V _F	I _F = ± 5 mA		1.1	1.4	V
	Terminal Capacitance	C _t	V = 0 V, f = 1 MHz		60		pF
Transistor	Collector to Emitter Dark Current	I _{CEO}	I _F = 0 mA, V _{CE} = 40 V			100	nA
Coupled	Current Transfer Ratio (I _C /I _F) *1	CTR	I _F = ± 5 mA, V _{CE} = 5 V	50	100	300	%
	CTR Ratio *2	CTR ₁ / CTR ₂	I _F = ± 5 mA, V _{CE} = 5 V	0.3	1.0	3.0	
	Collector Saturation Voltage	V _{CE(sat)}	I _F = ± 10 mA, I _C = 2 mA			0.3	V
	Isolation Resistance	R _{I-O}	V _{I-O} = 1 kV _{DC}	10 ¹¹			Ω
	Isolation Capacitance	C _{I-O}	V = 0 V, f = 1 MHz		0.4		pF
	Rise Time *3	t _r	V _{CC} = 5 V, I _C = 2 mA, R _L = 100 Ω		3		μs
	Fall Time *3	t _f			5		
	Turn-on Time *3	t _{on}			5		
	Turn-off Time *3	t _{off}			4		

Note: *1. CTR rank

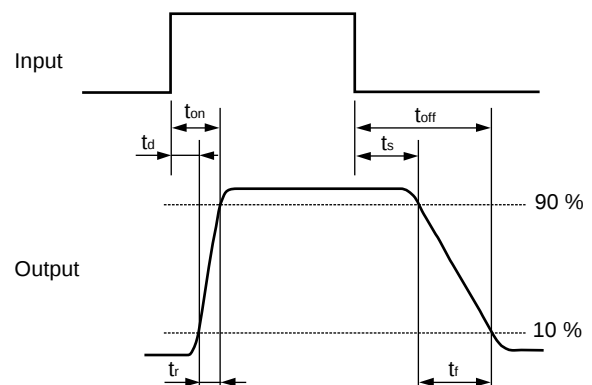
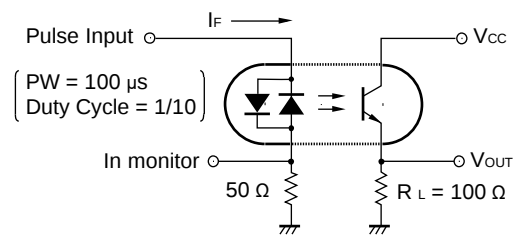
M: 50 to 150 (%)

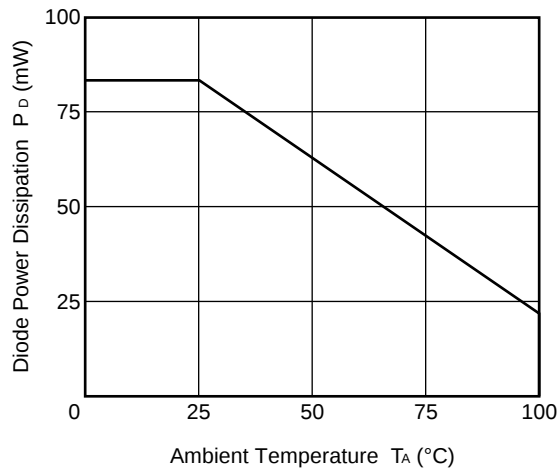
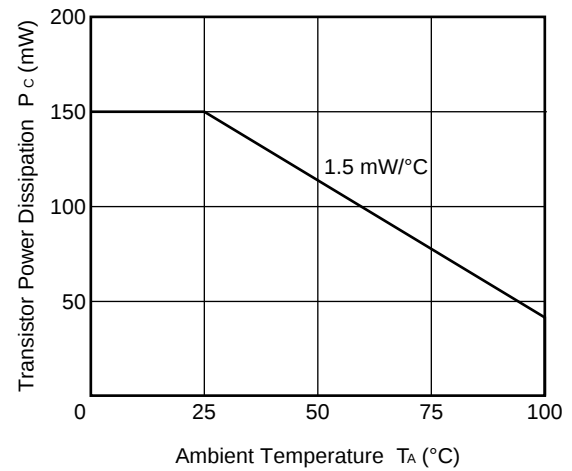
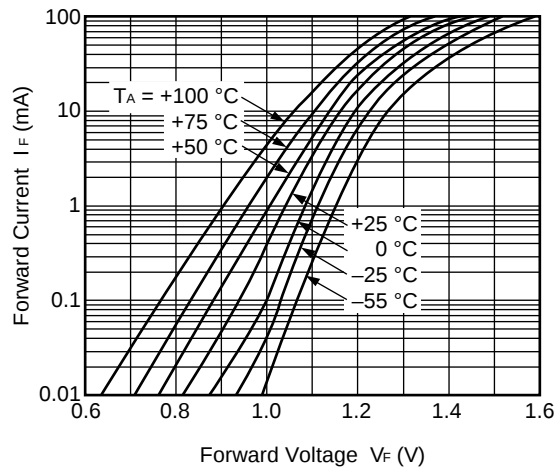
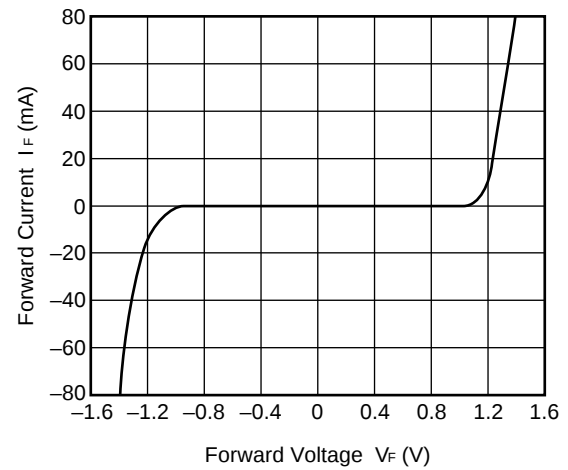
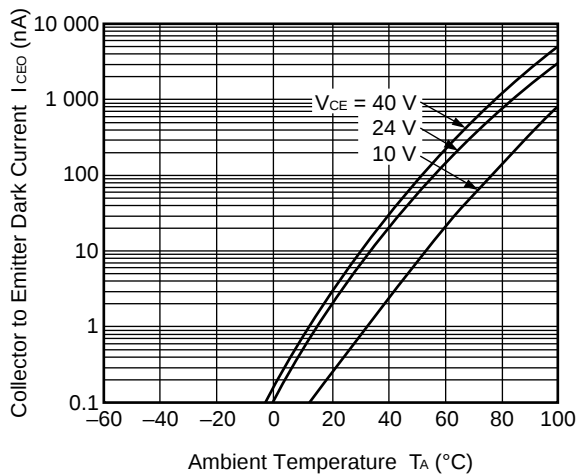
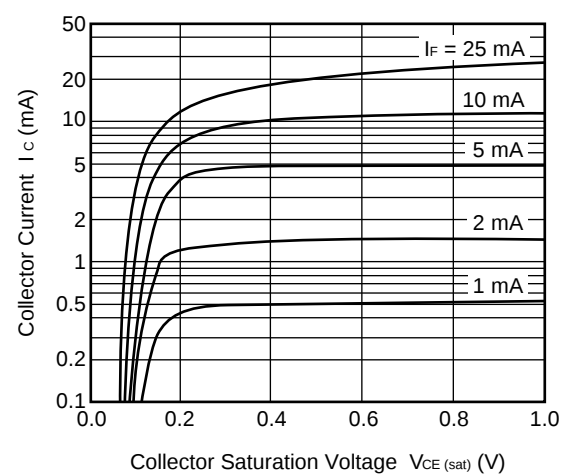
L: 100 to 300 (%)

N: 50 to 300 (%)

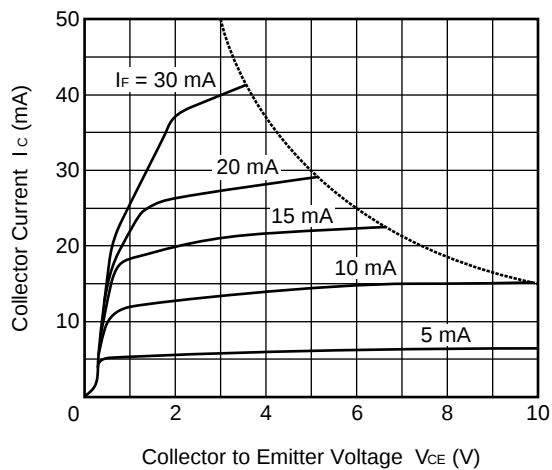
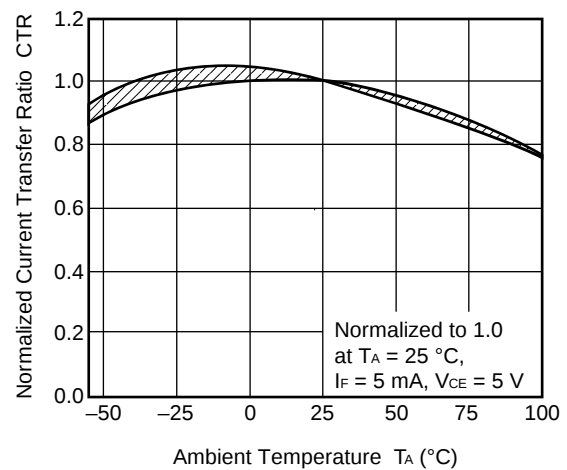
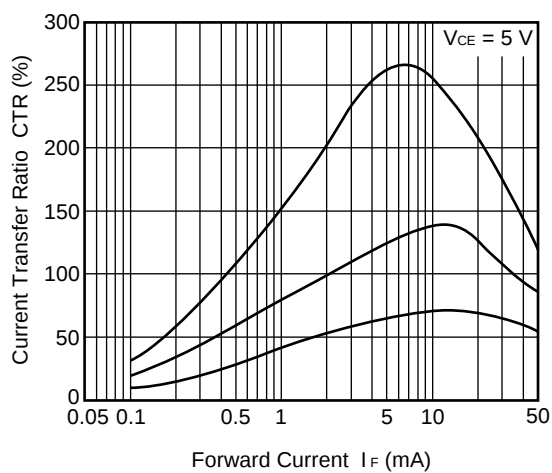
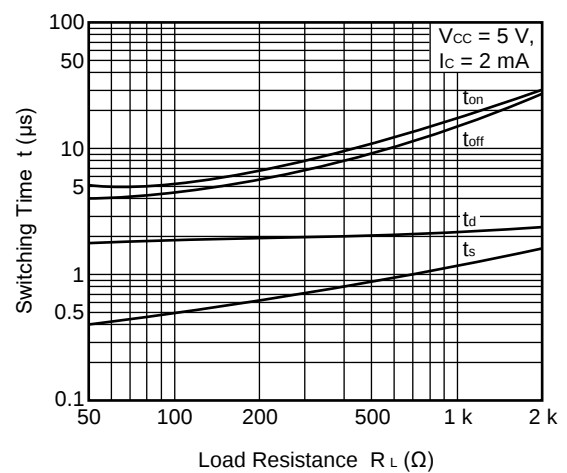
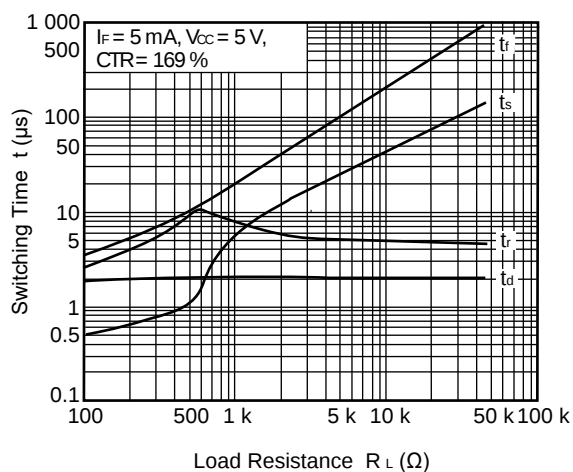
*2. CTR₁ = I_{C1}/I_{F1}, CTR₂ = I_{C2}/I_{F2}

*3. Test Circuit for Switching Time

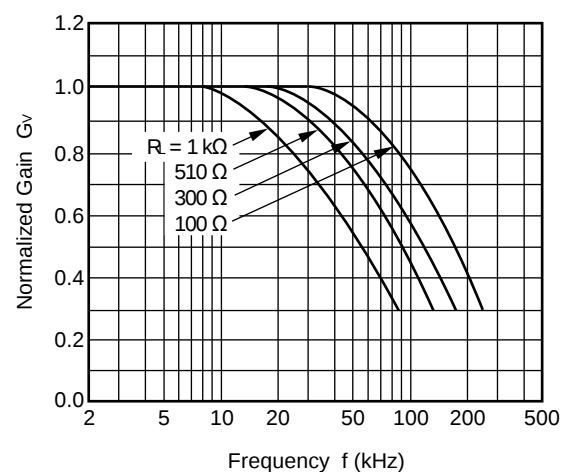


TYPICAL CHARACTERISTICS ($T_A = 25\text{ }^{\circ}\text{C}$, unless otherwise specified)DIODE POWER DISSIPATION vs.
AMBIENT TEMPERATURETRANSISTOR POWER DISSIPATION vs.
AMBIENT TEMPERATUREFORWARD CURRENT vs.
FORWARD VOLTAGEFORWARD CURRENT vs.
FORWARD VOLTAGECOLLECTOR TO EMITTER DARK
CURRENT vs. AMBIENT TEMPERATURECOLLECTOR CURRENT vs.
COLLECTOR SATURATION VOLTAGE

Remark The graphs indicate nominal characteristics.

COLLECTOR CURRENT vs.
COLLECTOR TO EMITTER VOLTAGENORMALIZED CURRENT TRANSFER
RATIO vs. AMBIENT TEMPERATURECURRENT TRANSFER RATIO vs.
FORWARD CURRENTSWITCHING TIME vs.
LOAD RESISTANCESWITCHING TIME vs.
LOAD RESISTANCE

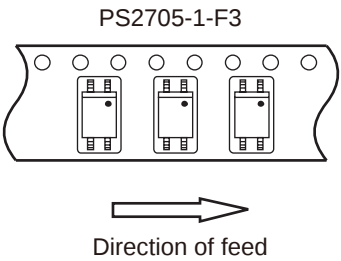
FREQUENCY RESPONSE



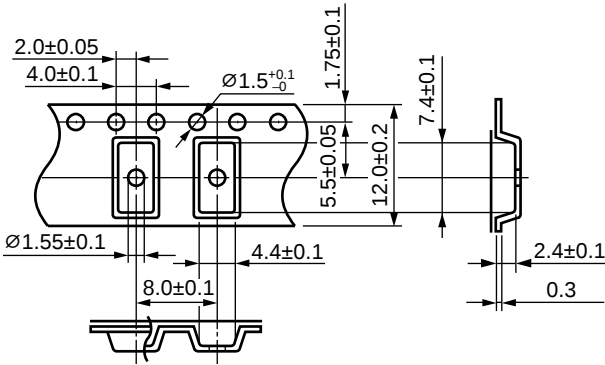
Remark The graphs indicate nominal characteristics.

TAPING SPECIFICATIONS (UNIT: mm)

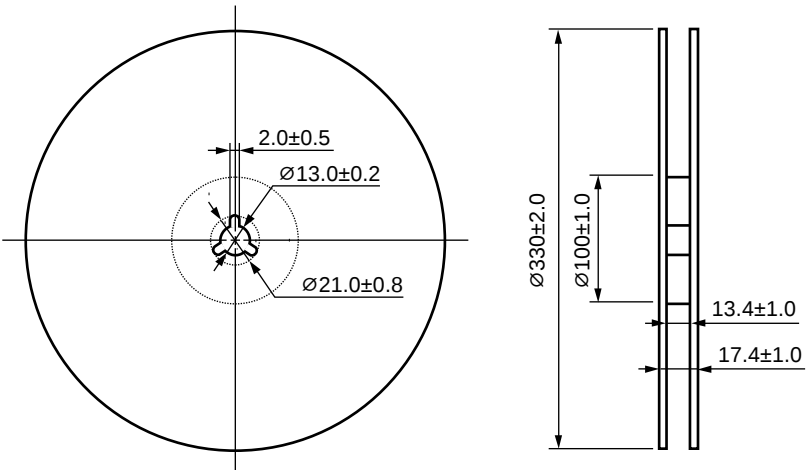
Taping Direction



Outline and Dimensions (Tape)

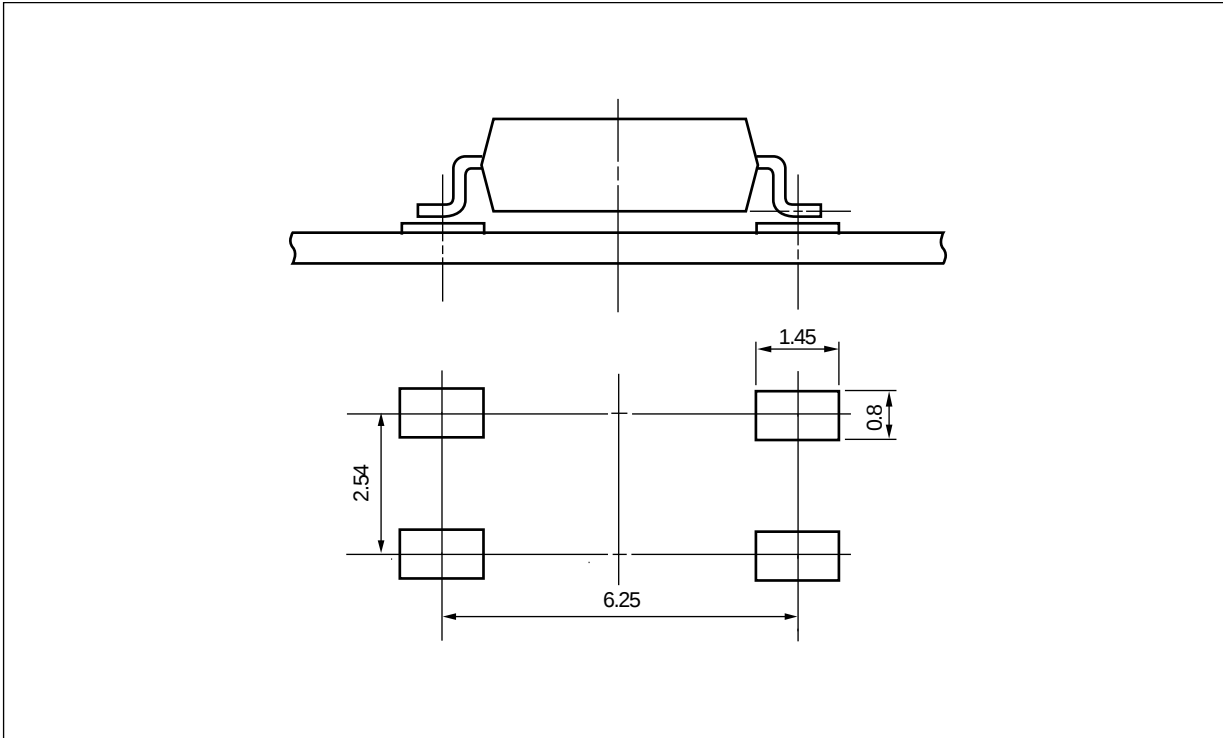


Outline and Dimensions (Reel)



Packing : 3 500 pcs/reel

RECOMMENDED MOUNT PAD DIMENSIONS (UNIT: mm)



Remark All dimensions in this figure must be evaluated before use.

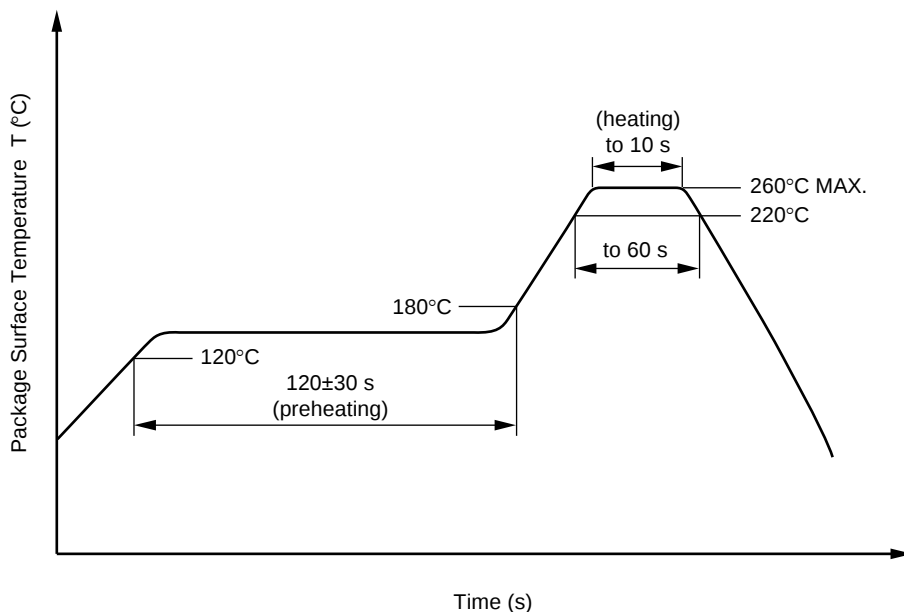
NOTES ON HANDLING

1. Recommended soldering conditions

(1) Infrared reflow soldering

- Peak reflow temperature 260 °C or below (package surface temperature)
- Time of peak reflow temperature 10 s or less
- Time of temperature higher than 220 °C 60 s or less
- Time to preheat temperature from 120 to 180 °C 120 ± 30 s
- Number of reflows Three
- Flux Rosin flux containing small amount of chlorine
(The flux with a maximum chlorine content of 0.2 Wt% is recommended.)

Recommended Temperature Profile of Infrared Reflow



(2) Wave soldering

- Temperature 260 °C or below (molten solder temperature)
- Time 10 s or less
- Preheating conditions 120 °C or below (package surface temperature)
- Number of times One (Allowed to be dipped in solder including plastic mold portion.)
- Flux Rosin flux containing small amount of chlorine (The flux with a maximum chlorine content of 0.2 Wt% is recommended.)

(3) Soldering by Soldering Iron

- Peak temperature (lead part temperature) 350 °C or below
- Time (per one side) 3 s or less
- Flux Rosin flux containing small amount of chlorine
(The flux with a maximum chlorine content of 0.2 Wt% is recommended.)
- Place 1.5 to 2.0 mm or more away from the root of the lead

(4) Cautions

- Flux cleaning Avoid cleaning with Freon- or halogen-based (chlorinated etc.) solvents.
- Fixing/Coating Do not use fixing agents or coatings containing halogen-based substances.

2. Cautions regarding noise

Be aware that when voltage is applied suddenly between the photocoupler's input and output or between collector-emitters at startup, the output transistor may enter the on state, even if the voltage is within the absolute maximum ratings.

3. Measurement conditions of current transfer ratios (CTR), which differ according to photocoupler

Check the setting values before use, since the forward current conditions at CTR measurement differ according to product.

When using products other than at the specified forward current, the characteristics curves may differ from the standard curves due to CTR value variations or the like. This tendency may sometimes be obvious, especially below $I_F = 1 \text{ mA}$.

Therefore, check the characteristics under the actual operating conditions and thoroughly take variations or the like into consideration before use.

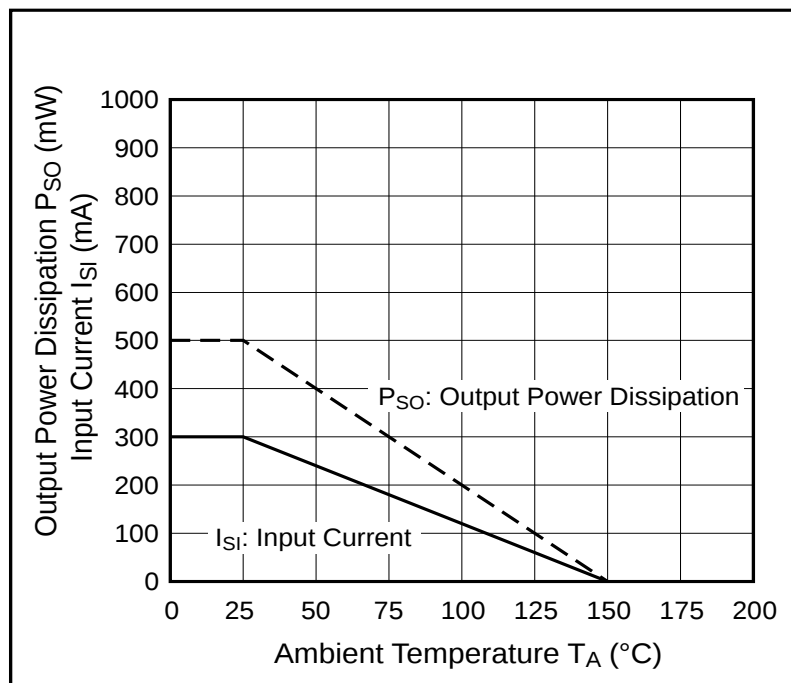
USAGE CAUTIONS

1. Protect against static electricity when handling.
2. Avoid storage at a high temperature and high humidity.

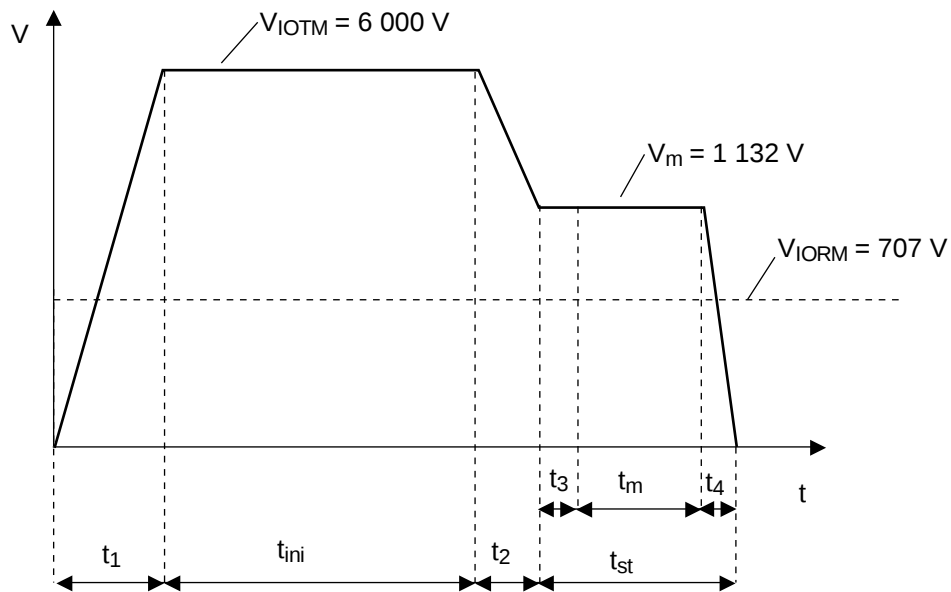
SPECIFICATION OF VDE MARKS LICENSE DOCUMENT

Parameter	Symbol	Rating	Unit
Climatic test class (IEC 60068-1/DIN EN 60068-1)		55/100/21	
Dielectric strength			
maximum operating isolation voltage	V_{IORM}	707	V_{peak}
Test voltage (partial discharge test, procedure a for type test and random test)	V_m	1 132	V_{peak}
$V_m = 1.6 \times V_{IORM}$, $q_{pd} < 5$ pC			
Test voltage (partial discharge test, procedure b for all devices)	V_m	1 326	V_{peak}
$V_m = 1.875 \times V_{IORM}$, $q_{pd} < 5$ pC			
Highest permissible overvoltage	V_{IOTM}	6 000	V_{peak}
Degree of pollution (IEC 60664-1/DIN EN 60664-1 (VDE 0110-1))		2	
Comparative tracking index (IEC 60112/DIN EN 60112 (VDE 0303-11))	CTI	175	
Material group (IEC 60664-1/DIN EN 60664-1 (VDE 0110-1))		III a	
Storage temperature range	T_{stg}	−55 to +150	°C
Operating temperature range	T_A	−55 to +100	°C
Isolation resistance, minimum value			
$V_{I-O} = 500$ V dc, $T_A = 25$ °C	R_{I-O} MIN.	10^{12}	Ω
$V_{I-O} = 500$ V dc, $T_A =$ maximum temperature of rating, at least 100 °C	R_{I-O} MIN.	10^{11}	Ω
Safety maximum ratings (maximum permissible in case of fault, see thermal derating curve)			
Maximum ambient temperature	T_S	150	°C
Maximum input current	I_{SI}	300	mA
Maximum output power dissipation	P_{SO}	500	mW
Isolation resistance, minimum value at $V_{I-O} = 500$ V dc, $T_A = T_S$	R_{I-O} MIN.	10^9	Ω

Dependence of maximum safety ratings on ambient temperature

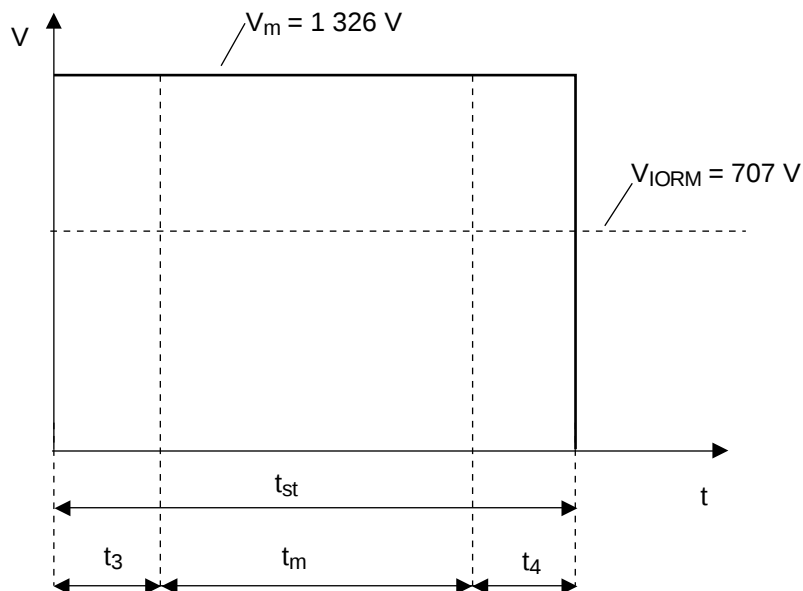


Method a) Destructive Test, Type and Sample Test



$t_1, t_2 = 1\text{ to }10\text{ sec}$
 $t_3, t_4 = 1\text{ sec}$
 $t_m = 10\text{ sec}$
 $t_{st} = 12\text{ sec}$
 $t_{ini} = 60\text{ sec}$

Method b) Non-destructive Test, 100% Production Test



$t_3, t_4 = 0.1\text{ sec}$
 $t_m = 1.0\text{ sec}$
 $t_{st} = 1.2\text{ sec}$

Caution GaAs Products	This product uses gallium arsenide (GaAs). GaAs vapor and powder are hazardous to human health if inhaled or ingested, so please observe the following points. • Follow related laws and ordinances when disposing of the product. If there are no applicable laws and/or ordinances, dispose of the product as recommended below. 1. Commission a disposal company able to (with a license to) collect, transport and dispose of materials that contain arsenic and other such industrial waste materials. 2. Exclude the product from general industrial waste and household garbage, and ensure that the product is controlled (as industrial waste subject to special control) up until final disposal. • Do not burn, destroy, cut, crush, or chemically dissolve the product. • Do not lick the product or in any way allow it to enter the mouth.
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